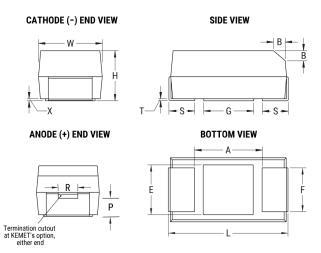


T489, Tantalum, MnO2 Tantalum, 1uF, 20%, 20 VDC, SMD, MnO2, Molded, Low Leakage, 6.63 Ohms, 3216, Height Max = 1.8mm



Click here for the 3D model.

Dimensions	,
Footprint	3216
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
Н	1.6mm +/-0.2mm
Т	0.13mm REF
S	0.8mm +/-0.3mm
F	1.2mm +/-0.1mm
Α	1.2mm MIN
В	0.4mm +/-0.15mm
E	1.3mm REF
G	1.1mm REF
Р	0.4mm REF
R	0.4mm REF
Χ	0.1mm +/-0.1mm

Packaging Specifications	
Packaging	T&R, 178mm
Packaging Quantity	2000

General Information	
Series	T489
Dielectric	MnO2 Tantalum
Style	SMD Chip
Description	SMD, MnO2, Molded, Low Leakage
Features	Low Leakage
RoHS	Yes
Termination	Tin
AEC-Q200	No
Component Weight	58.6 mg
Shelf Life	156 Weeks
MSL	1

Capacitance 1 uF Capacitance Tolerance 20% Voltage DC 20 VDC (85C), 13.4 VDC (125C) Temperature Range -55/+125°C Rated Temperature 85°C Dissipation Factor 4% 120Hz 25C Failure Rate N/A Resistance 6630 mOhms (100kHz 25C) Ripple Current 106 mA (rms, 100kHz 25C)	Specifications	
Voltage DC 20 VDC (85C), 13.4 VDC (125C) Temperature Range -55/+125°C Rated Temperature 85°C Dissipation Factor 4% 120Hz 25C Failure Rate N/A Resistance 6630 mOhms (100kHz 25C)	Capacitance	1uF
Temperature Range -55/+125°C Rated Temperature 85°C Dissipation Factor 4% 120Hz 25C Failure Rate N/A Resistance 6630 mOhms (100kHz 25C)	Capacitance Tolerance	20%
Rated Temperature 85°C Dissipation Factor 4% 120Hz 25C Failure Rate N/A Resistance 6630 mOhms (100kHz 25C)	Voltage DC	20 VDC (85C), 13.4 VDC (125C)
Dissipation Factor 4% 120Hz 25C Failure Rate N/A Resistance 6630 mOhms (100kHz 25C)	Temperature Range	-55/+125°C
Failure Rate N/A Resistance 6630 mOhms (100kHz 25C)	Rated Temperature	85°C
Resistance 6630 mOhms (100kHz 25C)	Dissipation Factor	4% 120Hz 25C
, ,	Failure Rate	N/A
Ripple Current 106 mA (rms, 100kHz 25C)	Resistance	6630 mOhms (100kHz 25C)
	Ripple Current	106 mA (rms, 100kHz 25C)
Leakage Current 0.5 uA (5min 25°C)	Leakage Current	0.5 uA (5min 25°C)

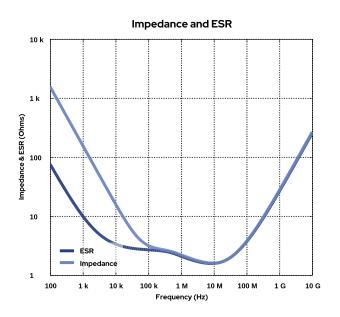
Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

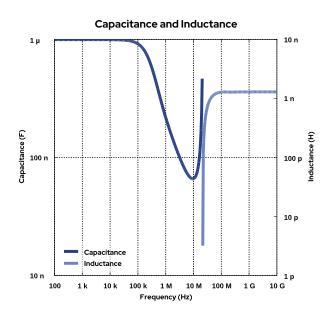


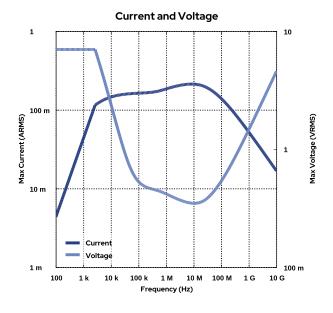
T489, Tantalum, MnO2 Tantalum, 1uF, 20%, 20 VDC, SMD, MnO2, Molded, Low Leakage, 6.63 Ohms, 3216, Height Max = 1.8mm

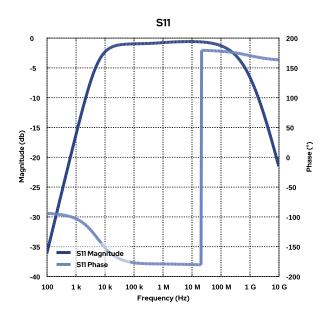
Simulations

For the complete simulation environment please visit K-SIM.



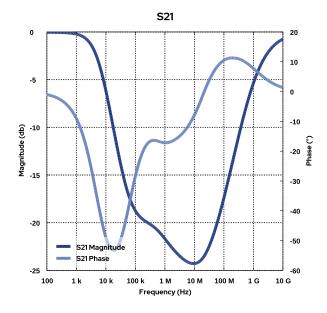








 $T489, Tantalum, MnO2\,Tantalum, 1\,uF, 20\%, 20\,VDC, SMD, MnO2, Molded, Low Leakage, 6.63\,Ohms, 3216, Height Max = 1.8mm$





T489, Tantalum, MnO2 Tantalum, 1 uF, 20%, 20 VDC, SMD, MnO2, Molded, Low Leakage, 6.63 Ohms, 3216, Height Max = 1.8mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.